## EKatherm® SILICON NITRIDE TECHNICAL DATA

			Silicon Nitride
Material properties	Norm	Symbol/Unit	EKatherm®
Density	DIN EN 623-2	ρ[g/cm³]	> 3,24
Porosity	DIN EN 623-2	P[%]	< 0,5
Mean grain size		[µm]	< 2
Aspect ratio (L/D)			3 - 5
Phase composition			β-Si <sub>3</sub> N <sub>4</sub> , Oxide
Vickers hardness	DIN EN 843-4	HV 1 [GPa]	14
Knoop hardness	DIN EN 843-4	HK 0.1 [GPa]	13,5
Young's modulus	DIN EN 843-2	E [GPa]	300
Weibull modulus	DIN EN 843-5	m	15
Flexural strength, 4-pt bending	DIN EN 843-1	σ <sub>в</sub> [MPa]	700
Compressive strength		σ <sub>D</sub> [MPa]	> 2500
Poisson ratio		ν	0,25
Fracture toughness (SENB)		K <sub>lc</sub> [MPa·m <sup>0,5</sup> ]	7
Coefficient of thermal expansion	DIN EN 821-1		
20°C - 500°C		α [10 <sup>-6</sup> /K]	2,0
500°C - 1000°C		α [10 <sup>-6</sup> /K]	4,0
Specific heat at 20°C	DIN EN 821-3	c <sub>p</sub> [J/g K]	0,7
Thermal conductivity at 20°C	DIN EN 821-2	λ[W/m K]	25
Thermal stress parameters	calculated		
$R_1 = \sigma_B \cdot (1 - v) / (\alpha \cdot E)$		[K]	875
$R_2 = R_1 \cdot \lambda$		[W/mm]	22
Specific electrical resistance at 20°C		ρ [Ω cm]	> 1011